



### **Description**

The SPC3 in SMTO-218 package provide the enhanced quality, easy manufacturing than typical through-hole TVS components. They can be connected in series and/or parallel to create various capability and flexible protection solutions.

## **Applications**

- Communication Equipment
- Security & Protection
- Industrial Control Equipment
- Power Supply
- Automotive Electronics
- New Energy
- Lightning Protection

### **Features**

- Bi-directional
- Low clamping and slope resistance
- For automatic pick and place assembly and reflow process to reduce the manufacturing cost and increase the soldering quality compared to axial leads package
- Patent pending package design
- Meet MSL level 1, per J-STD-020, LF Maximum peak of 245
   °C
- Pb-free E3 means 2<sup>nd</sup> level interconnect is Pb-free and the terminal finish material is tin (Sn)
- ESD follow IEC 61000-4-2
- Halogen free and RoHS compliant
- Tube or tape and reel pack options available

## **Functional Diagram**



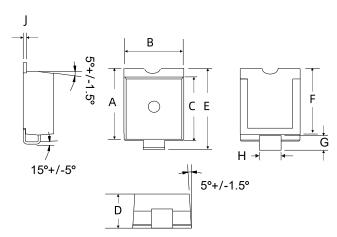
Bi-Directional

### Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted )

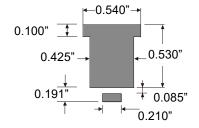
Part Number	Voltage Rev	Reverse	Vol	Voltage Curre	Test Current	Max. Clamping Voltage V <sub>CL</sub> @Peak Pulse Current (I <sub>PP</sub> )			Max. Temp Coefficient	Max. Capacitance
			V <sub>BR</sub> @I <sub>T</sub> Min Max		I <sub>T</sub>	V <sub>CL</sub>	I <sub>PP</sub> (8/20 μS)	Ι <sub>ΡΡ</sub> (10/350 μS)	of V <sub>BR</sub>	0 Bias 10KHz
			Min	Max			Min	Typical		
	(V)	(μΑ)	(	V)	(uA)	(V)	(A)	(A)	(%/°C)	(nF)
SPC3-066C	66	10	75	83	40	120	3000	800	0.1	6



# **Package Outline Dimensions (SMTO-218)**



Note: Coplanarity of solder side is controlled within 0.10mm



Mounting Pad Layout (Inch)

	Millim	eters	Inches		
Symbol	Min.	Max.	Min.	Max.	
А	15.78	16.63	0.621	0.655	
В	13.43	15.09	0.529	0.594	
С	13.83	14.24	0.544	0.561	
D	6.94	7.24	0.273	0.285	
Е	17.82	18.72	0.702	0.737	
F	14.40	14.76	0.567	0.581	
G	1.88	2.84	0.074	0.112	
Н	4.89	5.65	0.193	0.222	
J	0.72	0.85	0.028	0.033	

# **Maximum Ratings and Characteristics**

(Ratings at 25 °C ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Unit
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Operating Junction	$T_J$	-55 to 125	°C
Current Rating (8/20 μS wave)	I <sub>PP</sub>	10	kA

# **Physical Specifications**

Weight	Contact manufacturer			
Case	Epoxy molding compound encapsulated			
Terminal	Tin plated lead, solderability per MIL-STD-202 Method 208			

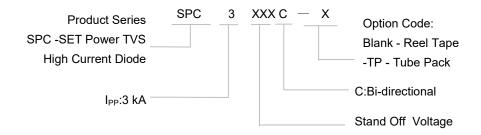
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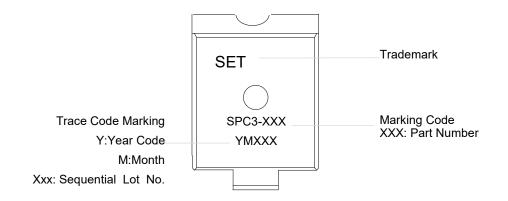
## **Environmental Specifications**

Temperature Cycling	JESD22-A104
HTRB	JESD22-A108
MSL	JESDEC-J-STD-020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-B106

### **Part Numbering System**



# Marking



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**SPC3 Series** 

## **Glossary**

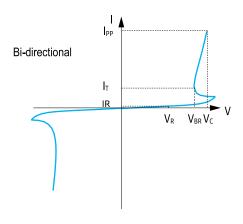
Item	Description
	Clamping Voltage
V <sub>C</sub>	Voltage across TVS in a region of low differential resistance that serves to limit the voltage across the device terminals.
V <sub>R</sub>	Reverse Stand-off Voltage Maximum voltage that can be applied to the TVS without operation. NOTE: It is also shown as $V_{\text{WM}}$ (maximum working voltage (maximum d.c. voltage)) and known as rated stand-off voltage ( $V_{\text{so}}$ ).
I <sub>R</sub>	Reverse Leakage Current  Current measured at $V_{R.}$ NOTE: Also shown as $I_{D}$ for stand-by current.
<b>V</b> <sub>BR</sub>	Breakdown Voltage Voltage across TVS at a specified current $I_T$ in the breakdown region.
I <sub>PPM</sub>	Rated Random Recurring Peak Impulse Current  Maximum-rated value of random recurring peak impulse current that may be applied to a device.
P <sub>M(AV)</sub>	Rated Average Power Dissipation  Maximum-rated value of power dissipation resulting from all sources, including transients and standby current, averaged over a short period of time.
P <sub>PPM</sub>	Rated Random Recurring Peak Impulse Power Dissipation  Maximum-rated value of the product of rated random recurring peak impulse current ( $I_{PPM}$ ) multiplies by specified maximum clamping voltage ( $V_C$ ).
Сл	Capacitance Capacitance across the TVS measured at a specified frequency and voltage.
<b>V</b> <sub>FS</sub>	Peak Forward Surge Voltage  Peak voltage across an TVS for a specified forward surge current ( $I_{FS}$ ) and time duration.  NOTE: Also shown as $V_{F.}$
I <sub>FS</sub>	Forward Surge Current  Pulsed current through TVS in the forward conducting region.  NOTE: Also shown as I <sub>F</sub> .
α <sub>V(BR)</sub>	Temperature Coefficient of Breakdown Voltage  The change of breakdown voltage divided by the change of temperature.
I <sub>PP</sub>	Peak pulse Current Peak pulse current value applied across the TVS to determine the clamping voltage $V_{\mathbb{C}}$ for a specified wave shape.
<b>I</b> <sub>T</sub>	Pulsed D.C. Test Current Test current for measurement of the breakdown voltage $V_{BR}$ . This is defined by the manufacturer and usually given in milliamperes with a pulse duration of less than 40 ms.  NOTE: Also shown as $I_{BR}$ .

--(GB-T 18802.321 / IEC 61643-321 / JESD210A)

# **TVS Diodes**

**Transient Voltage Suppression Diodes** 

### **I-V Curve Characteristics**



 $\mathsf{P}_{\mathsf{PPM}}$  - Peak Pulse Power Dissipation

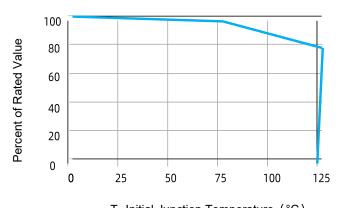
V<sub>R</sub> - Stand-off Voltage

V<sub>BR</sub> - Breakdown Voltage

V<sub>C</sub> - Clamping Voltage

I<sub>R</sub> - Reverse Leakage Current

### Performance Curve for Reference(T<sub>A</sub>=25 °C unless otherwise noted)



T<sub>J</sub>-Initial Junction Temperature (°C)

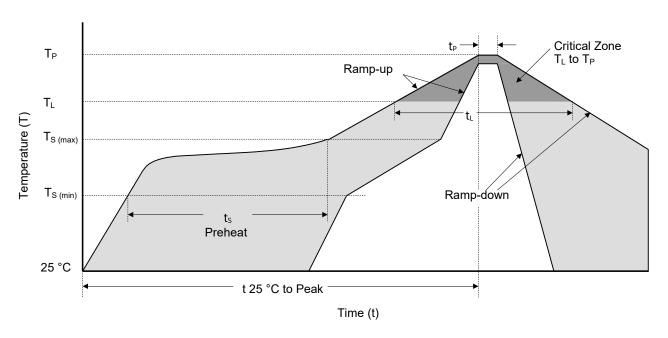
t<sub>r</sub>=rise time to peak value IPP-Peak Pulse Current-%IPP Peak Value 100 t<sub>d</sub>=decay time to half value t<sub>r</sub>×t<sub>d</sub>=8/20 µs Half Value 50  $0 t_r$ t-Time(µs)

FIGURE 1 Peak Power Derating

FIGURE 2 Pulse Waveform



# **Soldering Parameters**



**Reflowing Condition** 

Reflow Soldering	Lead-Free Assembly		
	Temperature Min (T <sub>S (min)</sub> )	150 °C	
Pre-heat	Temperature Max (T <sub>S (max)</sub> )	200 °C	
	Time (min to max) (t <sub>s</sub> )	60 ~ 120 seconds	
Average Ramp Up Rate (L	Average Ramp Up Rate (Liquidus Temp (TL) to Peak		
T <sub>S</sub> (max) to T <sub>L</sub>	T <sub>S</sub> (max) to T <sub>L</sub> Ramp-up Rate		
	Temperature (T <sub>L</sub> ) (Liquidus)	217 °C	
Reflow	Time (min to max) (t <sub>L</sub> )	60 ~ 150 seconds	
Peak Tempo	260 <sup>+0/-5</sup> °C		
Time of within 5 °C of Acti	20 ~ 40 seconds		
Ramp-do	6 °C / second max.		
Time from 25 °C to	8 Minutes max.		
Do Not	260 °C		

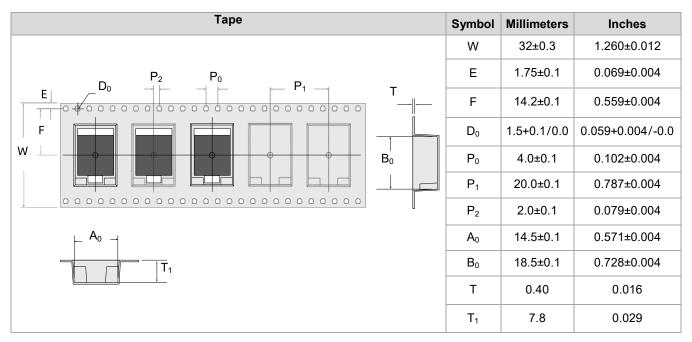
# Wave Soldering (Solder Dipping)

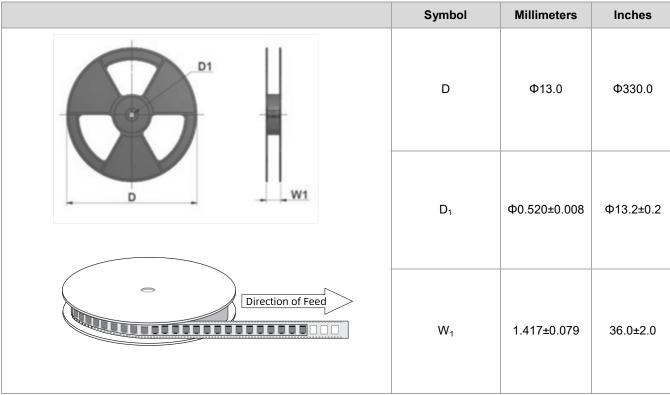
Peak Temperature	260 °C+0 /- 5 °C
Dipping Time	10 seconds
Soldering Number	1 time

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# **Packaging Information**





Part Number	Weight	Packaging Option	QTY's
SPC3-XXXXC	4.33 g	Tape & Reel – 32 mm/13" tape	400 PCS
SPC3-XXXXC-TP	4.33 g	Tube Pack	25 PCS /Tube

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### **Usage**

- 1.TVS must be operated in the specified ambient temp.
- 2.Do not clean the TVS with strong polar solvent such as ketone, esters, benzene and halogenated hydrocarbon, to avoid damaging the encapsulating layer.
- 3. Please do not apply severe vibration, shock or pressure to TVS, to avoid element cracking.

### Replacement

- 1.If TVS is visually damaged, please replace it.
- 2.TVS is a non-repairable product. For safety sake, please use equivalent TVS for replacement.

### **Storage**

- 1.Storage Temp. Range: (-55 to 150) °C.
- 2.Do not store the TVS at the high temp., high humidity or corrosive gas environment, to avoid influencing the solder- ability of the lead wires. The product shall be used up within 1 year after receiving the goods.

#### **Environmental Conditions**

- 1.TVS should not be exposed to the open air, nor direct sunshine.
- 2.TVS should avoid rain, water vapor or other condition of high temp. and high humidity.
- 3.TVS should avoid sand dust, salt mist, or other harmful gases.

# Max. Typical Capacitance of TVS

The typical capacitance of TVS is listed in the specifications. Designers may refer to it when designing TVS in High frequency circuit.

### **Installation Mechanical Stress**

- 1.Do not knock TVS when installing, to avoid mechanical damage.
- 2.Please do not apply severe vibration, shock or pressure to TVS, to avoid surface resin or element cracking.